

Centro Nacional de Microelectrónica (CNM)

Instituto de Microelectrónica de Barcelona(IMB)













IMB-CNM Presentation

- Centro Nacional de Microelectrónica
- Public Research Institute (CSIC)
- Located in Bellaterra, close to Barcelona (Spain)
- Devoted to Nano and Microelectronics
- Micro Nano Fabrication Facility (Clean Room)







Departments:

- Micro and Nano Systems
 - Silicon sensors and actuators
 - Nanotechnologies
- Systems Integration
 - Power devices
 - Circuits and systems design
 - Biomedical applications





IMB-CNM facilities

- Clean Room
 - 1.500 m², class 100 to 10.000
 - Micro and nano fabrication technologies
 - Three areas:
 - Pure (CMOS)
 - Noble metals allowed
 - Nanoelectronics
- Processes
 - 4" complete
 - 6" partial (no full thermal processes)
- Available technologies:
 - CMOS, BiCMOS, MCM-D, MEMS/NEMS, power devices
 - Bump bonding packaging
- Silicon micromachining
- Packaging
 - 200 m², class 100



- Characterization and test
 - DC and RF (up to 8 GHz)
 - Wafer testing
 - Thermography
 - Radiation testing
- Reverse Engineering
- Simulation
- CAD
- Mechanical Workshop
- Chemical sensors
- Bio-sensors
- Radiation sensors
- Optical sensors







Radiation Detectors group

- People
 - 6 permanent doctors
 - 2 contracted doctors
 - 4 PhD students
 - 2 Engineer



Activities started in 1996

Experiments

- Members of the RD50 CERN Collaboration
- ATLAS, ATLAS upgrade (sLHC)
- GRI (Gamma Radiation Imager)





- Contributions to Particle Physics CERN
- Security
- Medical
- Space
- > LabRad
- Flip Chip
- > 3D Printer

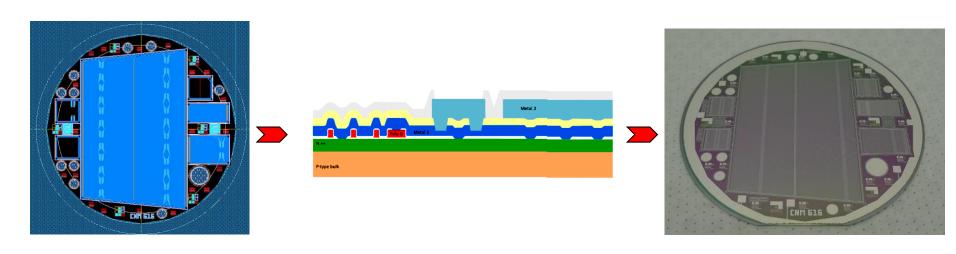


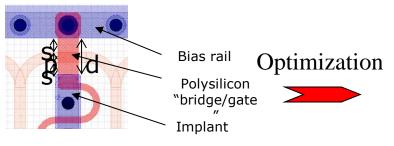


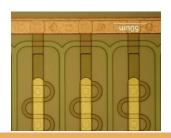


Particle Physics – Strip detectors

- Design, fabrication and optimization
 - Design and fabrication of full ATLAS-like sensors
 - Fabrication of sensors for the ATLAS Upgrade End Cap prototypes
 - Fabrication of sensors for the RD50 Collaboration





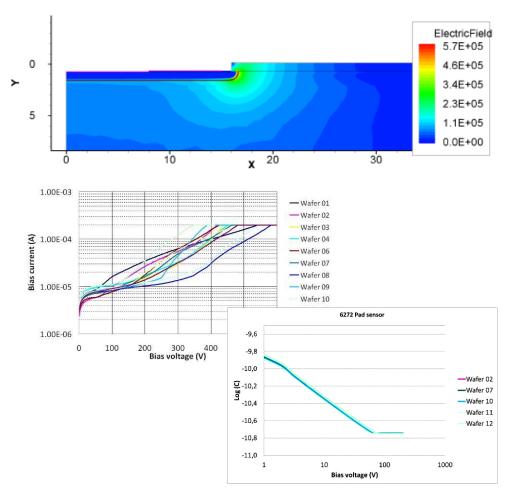


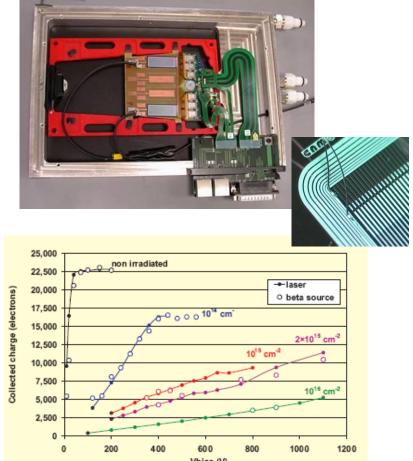




Particle Physics – Strip detectors

Simulation, characterization, irradiation

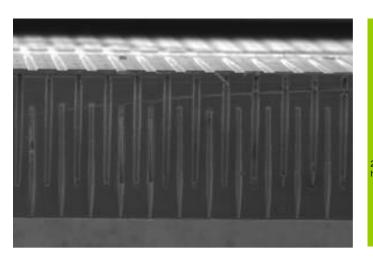


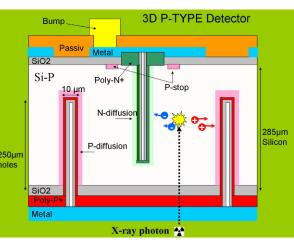




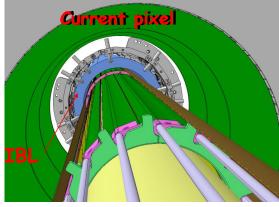
Particle Physics – 3D detectors

- Development and construction of pixel detectors for the IBL and ATLAS Upgrade experiment
- Fabrication of 72 wafers/year between 2011 y 2012









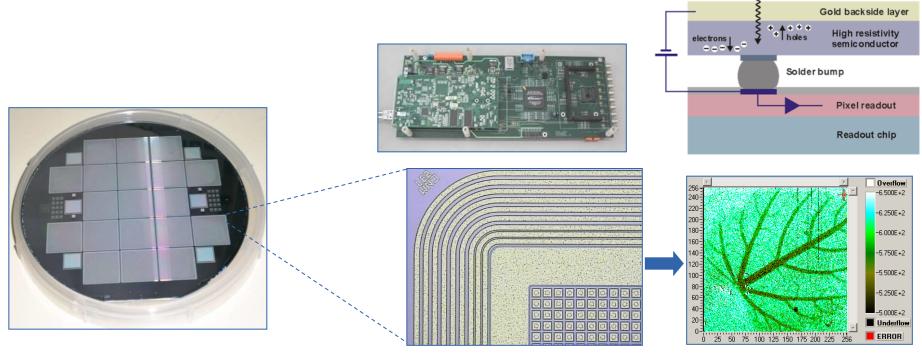




X-ray photon

Particle Physics - Pixel detectors

- Fabrication of pixel detectors in silicon
- CdTe detectors processing
- Bump bonding technology
- High density Flip-chip



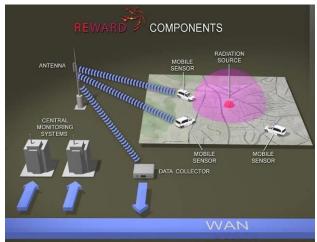


Security -REWARD Project

- Vehicle-borne autonomous units to detect radiation
- Radiation detectors for neutrons (Si) and gammas (CZT)
- Radioactive isotopes determination
- GPS localisation
- Secured communications(TETRA)
- Real-time processing data in a control center
- Objetive: to determine a radioactive area in real time







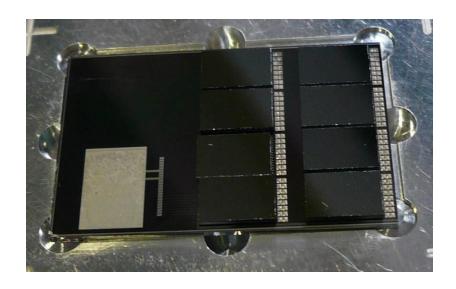


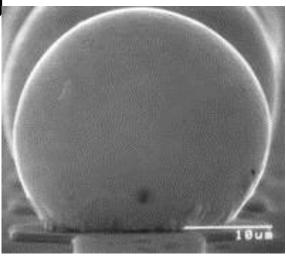


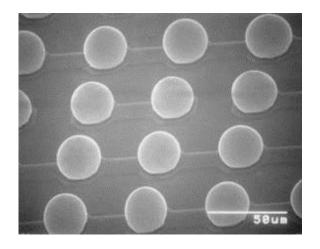


Flipchip Packaging

- Sn/Ag and Sn/Pb bump electroplating
- TiW/Cu electroplated UBM
- Ni/Au electroless UBM
- SET FC150 Pick&Place
- 1 micron placing accuracy
- Reflow in formic acid





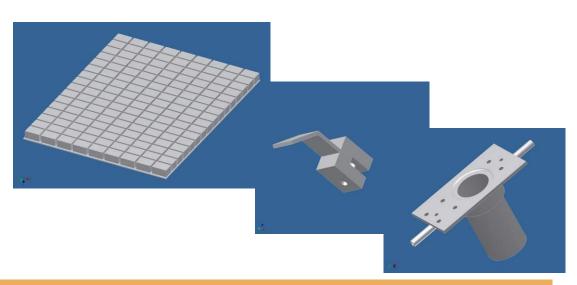






3D Rapid Manufacturing

- Polyamide Laser-sintering system
- EOS FORMIGA P 100
- From CAD to piece in few hours
 - Effective building volume: 20 cm x 25 cm x 33 cm
 - Resolution ~0.1 mm (vertical)







Medical Applications- GEM Detectors

- National funding for developing GEM detectors
- 3-year project in collaboration with IFAE and HIP (observer)

This is the reason to apply for CNM's membership into RD51 collaboration

